

Title (en)

Bath for electroplating silver-tin alloys

Title (de)

Bad zum galvanischen Abscheiden von Silber-Zinn-Legierungen

Title (fr)

Bain d'electrodéposition d'alliages argent-étain

Publication

**EP 0666342 B1 19980506 (DE)**

Application

**EP 95100167 A 19950107**

Priority

- DE 4403601 A 19940205
- DE 4440176 A 19941110

Abstract (en)

[origin: EP0666342A1] Ag-Sn Alloy electroplating bath contains 1-120 g/l Ag as soluble Ag cpd., 1-100 g/l Sn as soluble Sn cpd. 5-450 g/l mercaptoalkanoic acid (IA) and/or mercaptoalkanesulphonic acid (IB) and/or their salt(s) as chelating agent and 0-200 g/l conductive salt (II) and has a pH of 0-14.

IPC 1-7

**C25D 3/64**

IPC 8 full level

**C25D 3/56** (2006.01); **C25D 3/60** (2006.01); **C25D 3/64** (2006.01)

CPC (source: EP US)

**C25D 3/64** (2013.01 - EP US)

Cited by

DE10158227A1; DE10014852A1; EP2085502A1; EP0854206A1; US5911866A; WO03046260A3; WO2007060078A1; US7628903B1; US7938948B2; WO2020083799A1

Designated contracting state (EPC)

DE ES FR GB IT NL

DOCDB simple family (publication)

**EP 0666342 A1 19950809**; **EP 0666342 B1 19980506**; CA 2141090 A1 19950806; ES 2117995 T3 19980901; JP H07252684 A 19951003; US 5514261 A 19960507

DOCDB simple family (application)

**EP 95100167 A 19950107**; CA 2141090 A 19950125; ES 95100167 T 19950107; JP 1428595 A 19950131; US 38006695 A 19950130